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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/534,962	05/16/2005	Masayoshi Kondo	033036.088	1696
	7590 08/18/200 BRELL & RUSSELL	EXAMINER		
SUITE 3100, P.	ROMENADE II REE STREET, N.E.	PATEL, ISHWARBHAI B		
ATLANTA, GA			ART UNIT	PAPER NUMBER
			2841	
			MAIL DATE	DELIVERY MODE
			08/18/2008	PAPER

Please find below and/or attached an Office communication concerning this application or proceeding.

The time period for reply, if any, is set in the attached communication.

## Advisory Action Before the Filing of an Appeal Brief

Application No.	Applicant(s)	
10/534,962	KONDO ET AL.	
Examiner	Art Unit	

	Ishwar (I. B.) Patel	2841	
The MAILING DATE of this communication appe	ars on the cover sheet with the o	correspondence address	
THE REPLY FILED 05 August 2008 FAILS TO PLACE THIS AF	PPLICATION IN CONDITION FOR	ALLOWANCE.	
1. The reply was filed after a final rejection, but prior to or on application, applicant must timely file one of the following rapplication in condition for allowance; (2) a Notice of Appe for Continued Examination (RCE) in compliance with 37 C periods:	the same day as filing a Notice of replies: (1) an amendment, affidavi al (with appeal fee) in compliance	Appeal. To avoid abandon t, or other evidence, which with 37 CFR 41.31; or (3)	places the a Request
a) The period for reply expires <u>3</u> months from the mailing date	of the final rejection.		
b) The period for reply expires on: (1) the mailing date of this Adno event, however, will the statutory period for reply expire la Examiner Note: If box 1 is checked, check either box (a) or (I MONTHS OF THE FINAL REJECTION. See MPEP 706.07(f	dvisory Action, or (2) the date set forth tter than SIX MONTHS from the mailing b). ONLY CHECK BOX (b) WHEN THE ).	g date of the final rejection. FIRST REPLY WAS FILED \	WITHIN TWO
Extensions of time may be obtained under 37 CFR 1.136(a). The date of have been filed is the date for purposes of determining the period of extremely a CFR 1.17(a) is calculated from: (1) the expiration date of the set forth in (b) above, if checked. Any reply received by the Office later may reduce any earned patent term adjustment. See 37 CFR 1.704(b). NOTICE OF APPEAL	ension and the corresponding amount hortened statutory period for reply origi	of the fee. The appropriate exnally set in the final Office act	ktension fee ion; or (2) as
<ol> <li>The Notice of Appeal was filed on A brief in compl filing the Notice of Appeal (37 CFR 41.37(a)), or any exter Notice of Appeal has been filed, any reply must be filed with the complexity.</li> </ol>	sion thereof (37 CFR 41.37(e)), to	avoid dismissal of the app	
AMENDMENTS			
<ol> <li>The proposed amendment(s) filed after a final rejection, be (a) They raise new issues that would require further core (b) They raise the issue of new matter (see NOTE below</li> </ol>	sideration and/or search (see NO		ie
(c) They are not deemed to place the application in bett appeal; and/or	er form for appeal by materially rec	ducing or simplifying the is	sues for
(d) They present additional claims without canceling a converse NOTE: (See 37 CFR 1.116 and 41.33(a)).	orresponding number of finally reje	ected claims.	
4. The amendments are not in compliance with 37 CFR 1.12	21 See attached Notice of Non-Co	mpliant Amendment (PTO	I -324)
5. Applicant's reply has overcome the following rejection(s):		mphane, anonamone (r. 1 o.	_ 0 , .
6. Newly proposed or amended claim(s) would be all non-allowable claim(s).		timely filed amendment car	nceling the
7.  For purposes of appeal, the proposed amendment(s): a) [ how the new or amended claims would be rejected is prov The status of the claim(s) is (or will be) as follows:		l be entered and an explar	ation of
Claim(s) allowed: Claim(s) objected to: Claim(s) rejected: 17-20.			
Claim(s) withdrawn from consideration: <u>1-16 and 21-32</u> .			
AFFIDAVIT OR OTHER EVIDENCE			
<ol> <li>The affidavit or other evidence filed after a final action, but because applicant failed to provide a showing of good and was not earlier presented. See 37 CFR 1.116(e).</li> </ol>			
9. The affidavit or other evidence filed after the date of filing a entered because the affidavit or other evidence failed to or showing a good and sufficient reasons why it is necessary	vercome <u>all</u> rejections under appea	al and/or appellant fails to p	
10. ☐ The affidavit or other evidence is entered. An explanation REQUEST FOR RECONSIDERATION/OTHER	n of the status of the claims after e	ntry is below or attached.	
<ol> <li>The request for reconsideration has been considered but <u>See Continuation Sheet.</u></li> </ol>	does NOT place the application in	condition for allowance be	∋cause:
12. Note the attached Information <i>Disclosure Statement</i> (s). (13. Other:	PTO/SB/08) Paper No(s)		
August 14, 2008	/Ishwar (I. B.) Patel/ Primary Examiner, Art U	nit 2841	

Continuation of 11. does NOT place the application in condition for allowance because: Applicant's arguments filed on August 5, 2008 are reviewed carefully but not found to be persuasive.

Applicant argues that Shimizu discloses a wiring board wherein a bump (32) is formed for electrical connection to a land (38); see Figure 2, element 4. The electrical connection is established merely by physical contact and hence poor in reliability. In the present invention, conductor posts (105) and pads (106) are connected by a metal or an alloy so as to attain a high reliability; see Figure 1, especially Figure I (e) to I (g). See also [0090] of this application. This is point out in Claim 17.

This is not found to be persuasive.

Shimuzu, as applied to claim 17, disclose connection of the conductor posts (32, 39), which are made of metal, to the pads (38) with an adhesive medium (7). The claim recite "said conductor posts and pads are connected by a metal or an alloy through the medium of said adhesive layer." No specific connection structure is recited in the claim. As Shimuzu discloses the structure recited in the claim, Shimuzu meets the limitation.

Applicant further argues that in the present invention, the surface coating is provided only in the flexible portion. As a result, conductor posts can be short to attain high connection reliability, and the resulting wiring board can be thin because the multilayer portion includes no surface coating. This benefit could not have been predicted from either of the references. Because of the absence of a surface coating on the rigid portion in the present invention, the distance between the conductor posts and the conductor pads is short so that the reliability of the connection is high and this constitutes an advantage of the present invention. Shimizu does not disclose the wiring board as a flexible board, surface coating applied to the flexible portion but no surface coating applied on a multilayer portion.

This is not found to be persuasive.

Though, Shimizu does not disclose a flexible board, as applied to the claim rejection, board with flexible portion and rigid portion, as disclosed by Dixon is old and known in the art. Further, Dixon discloses a surface coating for the protection of the flexible part which is exposed. As the portion of the board in multilayer region is not exposed, no surface coating is applied. The instant claim recites no surface coating on a multilayer layer portion / or on rigid portion (as argued), and surface coating applied to flexible portion, which is not a part of multilayer portion / rigid portion. The modified board of Shimuzu (with the teaching of Dixon) discloses the structure as recited. Therefore, the modified board of Shimuzu meets the limitation.

Further, replacing the middle portion of the Shimuzu by a flexible board will facilitate bending of the board to be used where flexibility in operation is needed. Therefore, a person of ordinary skill in the art at the time of applicant's invention would have been motivated to replace the middle portion of Shimuzu by a flexible board to have the desired flexibility of the board.